



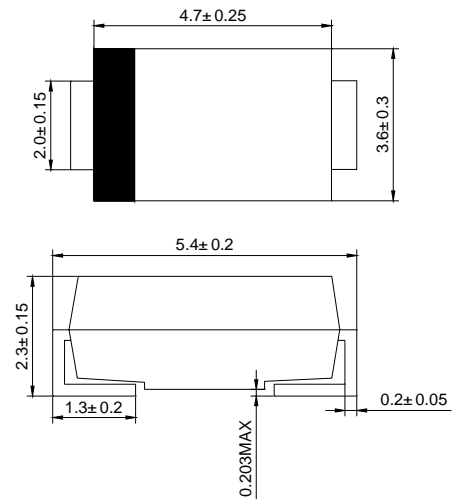
Features

- ◇ Plastic package has underwriters laborator flammability classification 94V-0
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering: 250°C/10 seconds at terminals

Mechanical Data

- ◇ Case: JEDEC DO-214AA, molded plastic over passivated chip
- ◇ Polarity: color band denotes cathode end
- ◇ Weight: 0.003 ounces, 0.093 gram

DO - 214AA(SMB)



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		RS1AB	RS1BB	RS1DB	RS1GB	RS1JB	RS1KB	RS1MB	UNITS	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V	
Maximum RMS voltage	V_{RWS}	35	70	140	280	420	560	700	V	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V	
Maximum average forward rectified current @ $T_L=90^\circ\text{C}$	$I_{F(AV)}$	1.0							A	
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	30.0							A	
Maximum instantaneous forward voltage at 1.0A	V_F	1.30							V	
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	I_R	5.0 50.0							μA	
Maximum reverse recovery time (NOTE 1)	t_{rr}	150			250		500		ns	
Typical junction capacitance (NOTE 2)	C_J	10					7.0			pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JL}$	105 32							$^\circ\text{C/W}$	
Operating junction and storage temperature range	$T_J T_{STG}$	- 55 ----- + 150							$^\circ\text{C}$	

NOTE: 1. Reverse recovery time test conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$

2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

3. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.2"X0.2"(5.0X5.0mm²) copper pad areas

Ratings AND Characteristic Curves

Fig. 1 — Forward Current Derating Curve

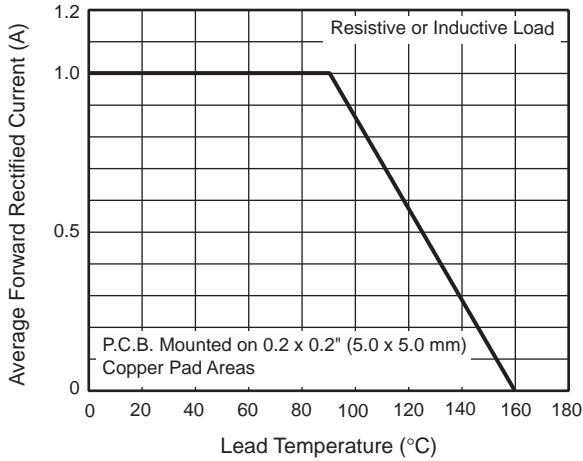


Fig. 2 — Maximum Non-Repetitive Peak Forward Surge Current

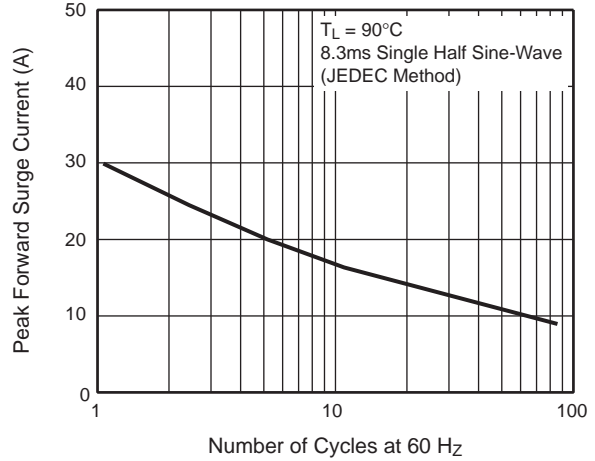


Fig. 3 — Typical Instantaneous Forward Characteristics

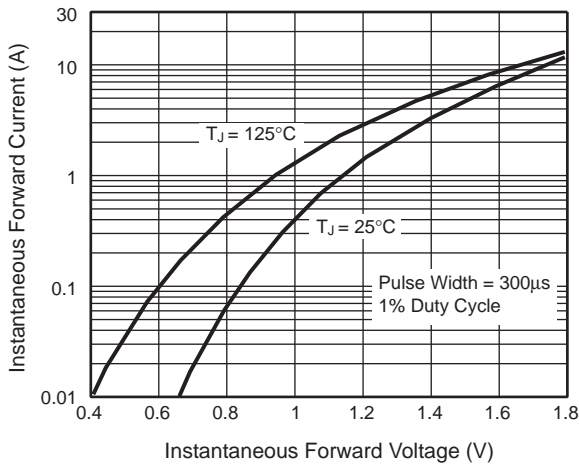


Fig. 4 — Typical Reverse Characteristics

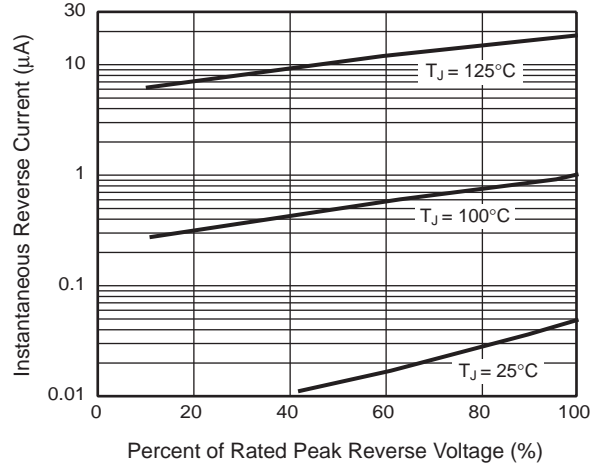


Fig. 5 — Typical Junction Capacitance

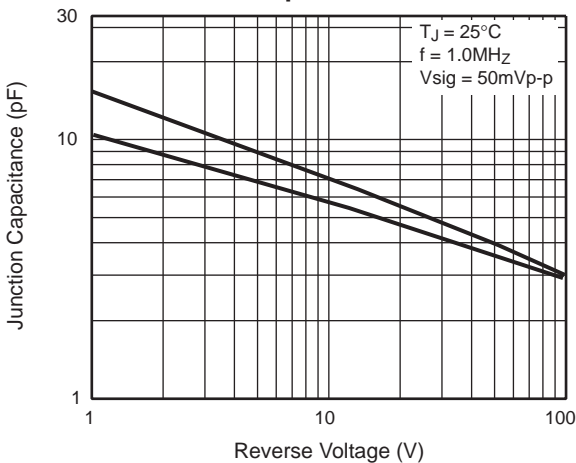


Fig. 6 — Typical Transient Thermal Impedance

